

AbstractMethod and system for pull testing of wire bonds

- 5 Disclosed is a method for pull testing of a wire bond. The method comprises steps of:
- (i) with a wire bonding tool, bonding an end of a wire to make a bond at a first location on a bonding surface comprising a conductive material, such that the bond completes an electrical circuit;
 - (ii) clamping the wire with a wire clamp;
 - 10 (iii) pulling the wire with the wire clamp to apply a predetermined pulling force;
 - (iv) detecting whether the electrical circuit is open; and
 - (v) if the electrical circuit is open, determining that there has been a bond failure, and automatically incrementing a bond failure count.

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[FIG. 3]